DECEMBER 1983-REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

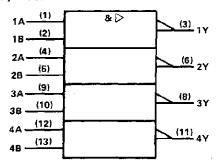
These devices contain four independent 2-input NAND buffer gates.

The SN5437, SN54LS37 and SN54S37 are characterized for operation over the full military range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7437, SN74LS37 and SN74S37 are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

	INP	UTS	ОИТРИТ
	Α	В	Y
Γ	Н	Н	L
	L	X	н
	X	L	Н

logic symbol†



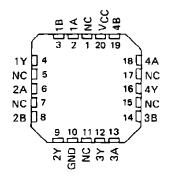
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5437, SN54LS37, SN54S37... J OR W PACKAGE SN7437... N PACKAGE SN74LS37, SN74S37... D OR N PACKAGE (TOP VIEW)

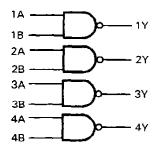
1A C 1B C 1Y C 2A C 2B C 2Y C	1 2 3 4 5	14 VCC 13 48 12 4A 11 4Y 10 3B 9 3A
2Y 🛚	6	9∐3A
GND 🗆	7	8 ☐ 3 Y

SN54LS37, SN54S37...FK PACKAGE (TOP VIEW)



NC - No internal connection

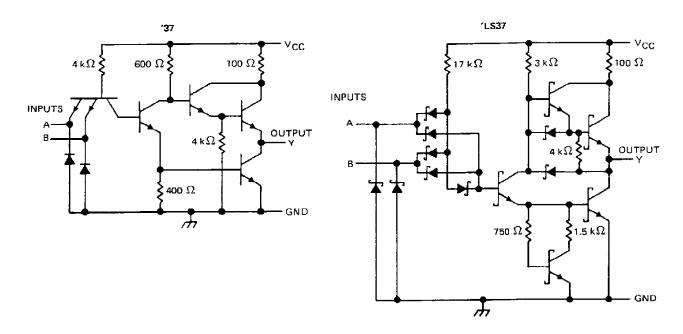
logic diagram

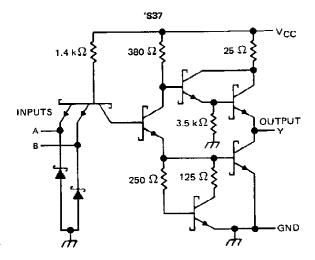


positive logic

 $Y = \overline{A \cdot B} \text{ or } Y = \overline{A} + \overline{B}$

schematics (each gate)





Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	1)	
Input voltage: '37, 'S37	***************************************	5.5 V
'LS37		7 V
Operating free-air temperature:	\$N54'	. –55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		. -65° C to 150° C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN5437	,		SN7437	•	UNIT
		MIN	NOM	MAX	MIN	MOM	MAX	CNII
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage		-	8.0			8.0	V
¹ ОН	High-level output current			- 1.2			- 1.2	mΑ
loL	Low-level output current			48			48	mΑ
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAGAMETER		TEST CONDIT	CONE T		SN5437			SN7437		
PARAMETER		TEST CONSTITUTES.				MAX	MIN	TYP \$	MAX	UNIT
V _{IK}	V _{CC} ≈ MIN,	I _I = - 12 mA				- 1.5			- 1.5	V
v _{он}	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 1.2 mA	2.4	3.3		2.4	3.3		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 48 mA		0.2	0.4		0.2	0.4	V
11	V _{CC} = MAX,	V ₁ = 6.5 V				1			1	mA
ΊΗ	V _{CC} = MAX,	V = 2.4 V			-	40			40	μА
ΊΙĻ	VCC = MAX,	V _I = 0.4 V				- 1.6	T		- 1.6	mA
los§	V _{CC} = MAX			- 20		- 70	- 18		- 70	mA
Гссн	V _{CC} ≈ MAX,	V ₁ = 0 V			9	15.5		9	15.5	mΑ
ICCL	V _{CC} = MAX,	V ₁ = 4.5 V			34	54		34	54	mΑ

- † For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
- ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{\Delta} = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
tPLH	A or B	×	$R_1 = 133 \Omega$,	C: - 45 p.F		13	22	กร
†PHL	Aora	,	nL - 133 12,	CL = 45 pF		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN54LS37, SN74LS37 QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS

recommended operating conditions

		S	SN54LS37			SN74LS37			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			$\overline{}$	
VIL	Low-level input voltage			0.7			8.0	V	
^Т ОН	High-level output current			-1.2			-1.2	mA	
loL	Low-level output current			12		-	24	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	IONS T	E	N54LS	37	s	N74LS	37	
FARAIVIE I EN	TEST CONDITIONS 1			MIN	MIN TYP# MA		MIN	TYP#	MAX	UNIT
٧ _{IK}	VCC = MIN,	i _I = -18 mA				- 1.5			- 1.5	V
V _{OH}	VCC = MIN,	V _{IL} = MAX,	lон = — 1.2 mA	2.5	3.4		2.7	3.4	_	V
٧	VCC = MIN,	V _{IH} = 2 V,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
V _{OL}	VCC = MIN.	V _{JH} = 2 V	IOL = 24 mA					0.35	0.5	\
<u> 11</u>	V _{CC} = MAX,	V _J = 7 V				0.1			0.1	mA
ЧH	VCC = MAX,	V _I = 2.7 V	<u> </u>			20		_	20	μΑ
ΙĮĽ	V _{CC} = MAX,	V _I = 0.4 V		_		- 0.4			- 0.4	mA
IOS §	V _{CC} = MAX			- 30		130	- 30		- 130	mA
Іссн_	VCC = MAX,	V ₁ = 0 V			0.9	2		0.9	2	mA
ICCL	V _{CC} = MAX,	V _I = 4.5 V			6	12		6	12	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
₹PLH	A or B	~	$R_1 = 667 \Omega$,	C. = 45 nE		12	24	ns
tPH∟	40.6		R _L = 667 Ω,	C _L = 45 pF		12	24	กร

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

	-	SN54S3	7		LIBUT		
	MIN	NOM	MAX	MIN	MOM	MAX	UNIT
VCC Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH High-level input voltage	2			2			V
VIL Low-level input voltage			8.0			8.0	٧
IOH High-level output current			– 3			- 3	mA
IOL Low-level output current			60			60	mA
TA Operating free-air temperature	-55		125	0		70	ас

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				•						
		TEST CONDIT	uana t		SN54S3	7		SN74S3	7	UNIT
PARAMETER		TEST CONDITIONS T	MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	UNII	
VIK	VCC = MIN,	I ₁ = - 18 mA			•	- 1.2			- 1.2	٧
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V,	l _{OH} = - 3 mA	2.5	3.4		2.7	3.4		
VoL	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 60 mA			0.5			0.5	V
tı	VCC = MAX,	V _I = 5.5 V				1			1	mA
Iн	V _{CC} = MAX,	V ₁ = 2.7 V				0.1			0.1	mA
IIL I	V _{CC} = MAX,	V _I = 0.5 V			-	-4			- 4	mA
IOS §	V _{CC} = MAX			50		- 225	- 50		- 225	mA
Гссн	V _{CC} = MAX,	V ₁ - 0 V	•		20	36		20	36	mA
CCL	V _{CC} = MAX,	V _I = 4.5		<u>-</u>	46	80		46	80	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed 100 milliseconds.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM	то	TEST CONDITIONS		MIN TYP	MAX	UNIT
	(INPUT)	(OUTPUT)					
tPLH			R _L = 93 Ω,	C; = 50 pF	4	6.5	ns
^t PHL	A or B	1 v L	_ ⊔Г – ⊒? ग़ः'	Ç[→ 90 pi	4	6.5	ns
^t PLH	AOID		R _L = 93 Ω,	C ₁ = 150 pF	6		กร
tPHL			20 75'	СГ - 100 Ы	6		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9754101Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9754101Q2A SNJ54LS 37FK	Samples
5962-9754101QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QC A SNJ54LS37J	Samples
5962-9754101QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QC A SNJ54LS37J	Samples
5962-9754101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QD A SNJ54LS37W	Samples
5962-9754101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QD A SNJ54LS37W	Samples
SN54LS37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS37J	Samples
SN54LS37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS37J	Samples
SN54S37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S37J	Samples
SN54S37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S37J	Samples
SN74LS37N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS37N	Samples
SN74LS37N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS37N	Samples
SN74LS37NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS37	Samples
SN74LS37NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS37	Samples
SN74S37D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S37	Samples
SN74S37D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S37	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74S37N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S37N	Samples
SN74S37N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S37N	Samples
SNJ54LS37FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9754101Q2A SNJ54LS 37FK	Samples
SNJ54LS37FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9754101Q2A SNJ54LS 37FK	Samples
SNJ54LS37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QC A SNJ54LS37J	Samples
SNJ54LS37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QC A SNJ54LS37J	Samples
SNJ54LS37W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QD A SNJ54LS37W	Samples
SNJ54LS37W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9754101QD A SNJ54LS37W	Samples
SNJ54S37FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 37FK	Samples
SNJ54S37FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 37FK	Samples
SNJ54S37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S37J	Samples
SNJ54S37J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S37J	Samples
SNJ54S37W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S37W	Samples
SNJ54S37W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S37W	Samples

PACKAGE OPTION ADDENDUM

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(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS37, SN54S37, SN74LS37, SN74S37:

Catalog: SN74LS37, SN74S37

Military: SN54LS37, SN54S37

NOTE: Qualified Version Definitions:



PACKAGE OPTION ADDENDUM

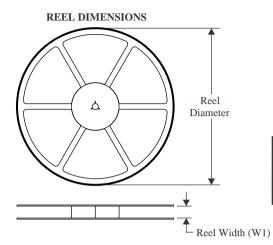
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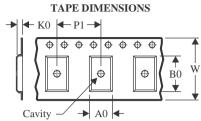
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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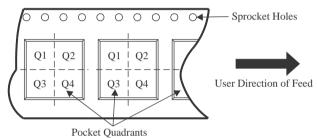
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS37NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS37NSR	SOP	NS	14	2000	356.0	356.0	35.0



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PACKAGE MATERIALS INFORMATION

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9754101Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9754101QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS37N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS37N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S37D	D	SOIC	14	50	506.6	8	3940	4.32
SN74S37N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S37N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS37FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS37W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54S37FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54S37W	W	CFP	14	25	506.98	26.16	6220	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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